



SPECIFICATION

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SPEC. NO.: PS-50305-XXXXX-XXX REVISION: J

PRODUCT NAME: 2.0 MM PITCH HEADER CONN.

PRODUCT NO: 50305;50308;50309;50310;50311;50312 ;50306 ;50421;
50422;51260;51332 series

PREPARED: Huang, Shun Sen DATE: 2019.11.27	CHECKED: Lu, Jing Quan DATE: 2019.11.27	APPROVED: hsieh, fu yu DATE: 2019.11.27
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1 Revision History

Rev.	ECN #	Revision Description	Prepared	Date
O	ECN-0812218	NEW RELEASE	JASON	2008.12.25
A	ECN-0907017	REFER TO 50306 SERIES	JASON	2009.7.3
B	ECN-1001070	ADD Manual Soldering Heat	JASON	2010.01.14
C	ECN-1005196	REFER TO 50421 、50422 SERIES AND REVISED Mating Force	JASON	2010.05.25
D	ECN-1006209	REVISED Current SPEC	Huanty	2010.07.14
E	ECN-1401180	ADD WORKING VOLTAGE	XUFEI	2014.1.10
F	ECN-1408282	ADD 51260 SERIES	GUKEQING	2014.08.27
G	ECN-1608117	Revise Mating Force,ADD Durability	XIAOXIONG	2016.08.09
H	ECN-1803459	ADD 51332 SERIES	Huang,Shun Sen	2018.03.26
J	ECN-1911495	Revise hock to Shock	Huang,Shun Sen	2019.11.27

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2 SCOPE

This specification covers performance, tests and quality requirements for wire to board connector. ACES P/N:50305;50308;50309;50310;50311;50312;50306;50421;50422,51260series.

3 APPLICABLE DOCUMENTS

EIA-364 ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

4.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable product drawing.

4.2 Materials and Finish

- 4.2.1 Contact: High performance copper alloy (Brass)
Finish: (a) Contact Area: Refer to the drawing.
(b) Under plate: Refer to the drawing.

4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0

4.3 Ratings

- 4.3.1 Working voltage less than 36 volts (per pin)
4.3.2 Voltage: 200 Volts AC (per pin)
Current: AWG#26 DC 3 Amperes (per pin)
AWG#28 DC 2.5 Amperes (per pin)
AWG#30 DC 1.5 Amperes (per pin)
4.3.3 Operating Temperature : -40°C to +85°C

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5 Performance

5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.
ELECTRICAL		
Item	Requirement	Standard
Low Level Contact Resistance	55 m Ω Max.(initial)per contact 25 m Ω Max. Change allowed	Mate connectors, measure by dry circuit, 20mV Max., 10mA Max. (EIA-364-23)
Insulation Resistance	1000 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	500 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)
Temperature rise	30°C Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70 METHOD 1, CONDITION1)
MECHANICAL		
Item	Requirement	Standard
Durability	30 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3 mm/min. (EIA-364-09)
Mating / Unmating Forces	Mating Force: 700 gf Max./CKT Unmating Force: 150 gf Min./CKT	Operation Speed : 25 ± 3 mm/minute.. Measure the force required to mate/Unmate connector. (EIA-364-13)
Terminal / Housing Retention Force	500 gf MIN.	Apply axial pull out force at the speed rate of 25 ± 3 mm/minute. On the terminal assembled in the housing.

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Contact Retention Force	0.50Kgf Min.	Operation Speed : 25.4 ± 3 mm/minute. Measure the contact retention force with Tensile strength tester.
Fitting Nail /Housing Retention Force	0.1kgf MIN.	Apply axial pull out force at the speed rate of 25.4 ± 3 mm/minute. On the fitting nail assembled in the housing.
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)

ENVIRONMENTAL

Item	Requirement	Standard
Resistance to Reflow Soldering Heat	See Product Qualification and Test Sequence Group 9 (Lead Free)	Pre Heat : 150°C~180°C, 60~120sec. Heat : 230°C Min., 40sec Min. Peak Temp. : 260°C Max, 10sec Max.
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +0/-3 °C, 30 minutes +85 +3/-0 °C, 30 minutes (EIA-364-32, test condition I)

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Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31, Condition A, Method II)
Temperature life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85°C for 96 hours. (EIA-364-17, Test condition A)
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C (I) Gold Flash for 8 hours (II) Gold Plating 5u" For 96 hours (EIA-364-26, Test condition B)
Solder ability	Solder able area shall have minimum of 75% solder coverage.	Subject the test area of contacts into the flux for 5-10 sec. And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)
Hand Soldering Temperature Resistance	Appearance: No damage	T ≥ 350°C, 3 sec at least.

Note. Flowing Mixed Gas shall be conduct by customer request.

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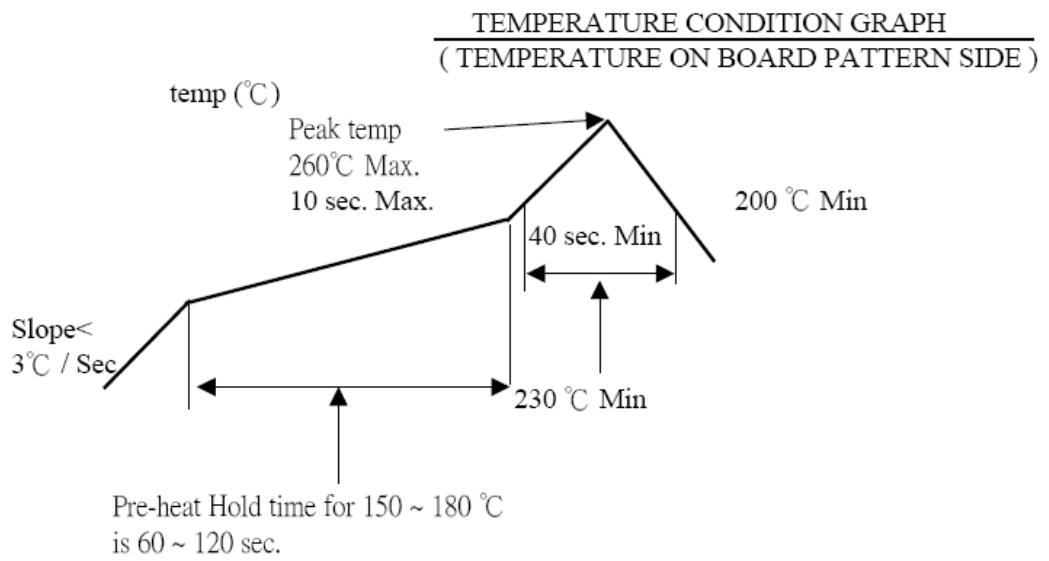
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6 INFRARED REFLOW CONDITION

6.1. Lead-free Process



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7 PRODUCT QUALIFICATION AND TEST SEQUENCE

Test or Examination	Test Group									
	1	2	3	4	5	6	7	8	9	10
	Test Sequence									
Examination of Product				1、7	1、6	1、4			1	1
Low Level Contact Resistance		1、5	1、4	2、10	2、9	2、5			3	
Insulation Resistance				3、9	3、8					
Dielectric Withstanding Voltage				4、8	4、7					
Temperature rise	1									
Mating / Unmating Forces		2、4								
Durability		3								
Contact Retention Force								1		
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature life					5					
Salt Spray						3				
Solder ability							1			
Terminal / Housing Retention Force								1		
Fitting Nail /Housing Retention Force								2		
Resistance to Soldering Heat									2	
Hand Soldering Temperature Resistance										2
Sample Size	2	4	4	4	4	4	2	4	4	4